## LM148, LM248, LM348 QUADRUPLE OPERATIONAL AMPLIFIERS

SLOS058C - OCTOBER 1979 - REVISED DECEMBER 2002

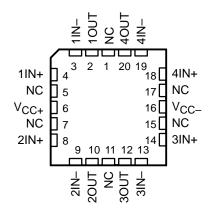
- µA741 Operating Characteristics
- Low Supply-Current Drain . . . 0.6 mA Typ (per amplifier)
- Low Input Offset Voltage
- Low Input Offset Current
- Class AB Output Stage
- Input/Output Overload Protection
- Designed to Be Interchangeable With Industry Standard LM148, LM248, and LM348

### description/ordering information

The LM148, LM248, and LM348 are quadruple, independent, high-gain, internally compensated operational amplifiers designed to have operating characteristics similar to the  $\mu$ A741. These amplifiers exhibit low supply-current drain and input bias and offset currents that are much less than those of the  $\mu$ A741.

LM148J PACKAGE LM248D OR N PACKAGE LM348D, N, OR NS PACKAGE (TOP VIEW)											
10UT[		U,	140UT								
	1	14	-								
1IN-[	2	13	] 4IN–								
1 IN+[	3	12	] 4IN+								
V <sub>CC+</sub> [	4	11	] v <sub>cc-</sub>								
2IN+[	5	10	] 3IN+								
2IN-[	6	9	] 3IN–								
20UT[	7	8	] 30UT								

#### LM148 ... FK PACKAGE (TOP VIEW)



NC - No internal connection

т <sub>А</sub>	V <sub>IO</sub> max AT 25°C	PACK	AGE <sup>†</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
		PDIP (N)	P (N) Tube of 25 LM348N		LM348N	
000 to 7000	6 m)/		Tube of 50	LM348D	1 10 40	
0°C to 70°C	6 mV	SOIC (D)	Reel of 2500	LM348DR	LM348	
		SOP (NS)	Reel of 2000	LM348NSR	LM348	
		PDIP (N)	Tube of 25	LM248N	LM248N	
–25°C to 85°C	6 mV		Tube of 50	LM248D	1.140.40	
		SOIC (D)	Reel of 2500	LM248DR	LM248	
–55°C to 125°C	E>/	CDIP (J)	Tube of 25	LM148J	LM148J	
-55°C 10 125°C	5 mV	LCCC (FK)	Tube of 50	LM148FK	LM148FK	

#### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

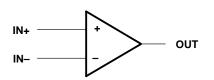


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## LM148, LM248, LM348 QUADRUPLE OPERATIONAL AMPLIFIERS

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### symbol (each amplifier)



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage V/s - (ase Note 1); IM149	22.1/
Supply voltage, V <sub>CC+</sub> (see Note 1): LM148	
LM248, LM348	
Supply voltage, V <sub>CC</sub> (see Note 1): LM148	–22 V
LM248, LM348	–18 V
Differential input voltage, V <sub>ID</sub> (see Note 2): LM148	
LM248, LM348	
Input voltage, V <sub>I</sub> (either input, see Notes 1 and 3): LM148	
LM248, LM348	
Duration of output short circuit (see Note 4)	
Operating virtual junction temperature, T	
Package thermal impedance, $\theta_{JA}$ (see Notes 5 and 6): D package	
N package	
NS package	
Package thermal impedance, $\theta_{JC}$ (see Notes 7 and 8): FK package	
J package	
Case temperature for 60 seconds: FK package	
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: J package	
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: D, N, or NS package	
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C
5	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, unless otherwise noted, are with respect to the midpoint between V<sub>CC+</sub> and V<sub>CC-</sub>.

2. Differential voltages are at IN+ with respect to IN-.

- 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or the value specified in the table, whichever is less.
- 4. The output may be shorted to ground or either power supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
- 5. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperautre is  $P_D = (T_J(max) T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
- 6. The package thermal impedance is calculated in accordance with JESD 51-7.
- 7. Maximum power dissipation is a function of  $T_J(max)$ ,  $\theta_{JC}$ , and  $T_C$ . The maximum allowable power dissipation at any allowable ambient temperautre is  $P_D = (T_J(max) T_C)/\theta_{JC}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.
- 8. The package thermal impedance is calculated in accordance with MIL-STD-883.

### recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V <sub>CC+</sub>	4	18	V
Supply voltage, V <sub>CC</sub> _	-4	-18	V



PARAMETER TEST CONDITIONS <sup>†</sup> LM148 LM248									LM248		I			
	PARAMETER	1	EST CONDITIO	NSI	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
				25°C		1	5		1	6		1	6	.,
VIO	Input offset voltage	Λ <sup>O</sup> = 0	ļ	Full range			6			7.5			7.5	mV
				25°C		4	25		4	50		4	50	
IIO	Input offset current	VO = 0		Full range			75			125			100	nA
				25°C		30	100		30	200		30	200	
IIB	Input bias current	VO = 0		Full range			325			500			400	nA
VICR	Common-mode input voltage range			Full range	±12			±12			±12			V
		R <sub>L</sub> = 10 kΩ	2	25°C	±12	±13		±12	±13		±12	±13		
	Maximum peak output voltage	$R_L \ge 10 \ k\Omega$	2	Full range	±12			±12			±12			
VOM	swing	$R_L = 2 k\Omega$		25°C	±10	±12		±10	±12		±10	±12		V
		$R_L \ge 2 \ k\Omega$		Full range	±10			±10			±10			
	Large-signal differential voltage	$V_{O} = \pm 10 \text{ V},$ RL= $\geq 2 \text{ k}\Omega$		25°C	50	160		25	160		25	160		V/mV
A <sub>VD</sub>	amplification			Full range	25			15			15			
r <sub>i</sub>	Input resistance‡			25°C	0.8	2.5		0.8	2.5		0.8	2.5		M۵
B <sub>1</sub>	Unity-gain bandwidth	$A_{VD} = 1$		25°C		1			1			1		MH
<sup>¢</sup> m	Phase margin	$A_{VD} = 1$		25°C		60°			60°			60°		
		VIC = VICF	əmin,	25°C	70	90		70	90		70	90		
CMRR	Common-mode rejection ratio	$V_0 = 0$		Full range	70			70			70			dE
	Supply-voltage rejection ratio	$V_{CC+} = \pm 9$	9 V to ±15 V,	25°C	77	96		77	96		77	96		
<b>k</b> SVR	$(\Delta V_{CC\pm}/\Delta V_{IO})$	$V_0 = 0$		Full range	77			77			77			dE
los	Short-circuit output current			25°C		±25			±25			±25		m/
ICC	Supply current (four amplifiers)	No load	$V_{O} = 0$ $V_{O} = V_{OM}$	25°C		2.4	3.6		2.4	4.5		2.4	4.5	m/
V <sub>01</sub> /V <sub>02</sub>	Crosstalk attenuation	f = 1 Hz to 2		25°C		120			120			120		dl

### electrical characteristics at specified free-air temperature, $V_{CC+} = \pm 15$ V (unless otherwise noted)

<sup>†</sup> All characteristics are measured under open-loop conditions with zero common-mode input voltage, unless otherwise specified. Full range for T<sub>A</sub> is -55°C to 125°C for LM148, -25°C to 85°C for LM248, and 0°C to 70°C for LM348.

<sup>‡</sup>This parameter is not production tested.

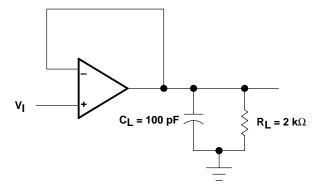
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## operating characteristics, V\_{CC\pm} = $\pm 15$ V, T\_A = 25°C

	PARAMETER	Т	EST CONDITIO	MIN	TYP	MAX	UNIT	
SR	Slew rate at unity gain	$R_L = 2 k\Omega$ ,	C <sub>L</sub> = 100 pF,	See Figure 1		0.5		V/µs

### PARAMETER MEASUREMENT INFORMATION





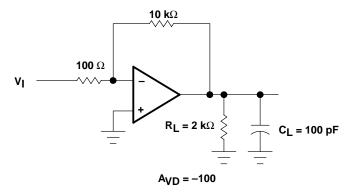


Figure 2. Inverting Amplifier





### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM148 MW8	ACTIVE	WAFERSALE	YS	0	1	RoHS & Green	(6) Call TI	Level-1-NA-UNLIM	-55 to 125		Samples
LM148FKB	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	LM148FKB	Samples
LM148J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	LM148J	Samples
LM148JB	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	LM148JB	Samples
LM248D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-25 to 85	LM248	
LM248DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM248	Samples
LM248N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-25 to 85	LM248N	Samples
LM348D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	0 to 70	LM348	
LM348DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM348	Samples
LM348DRE4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM348	Samples
LM348DRG4	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM348	Samples
LM348N	ACTIVE	PDIP	Ν	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	LM348N	Samples
LM348NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	LM348	Samples

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.



## PACKAGE OPTION ADDENDUM

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

<sup>(6)</sup> Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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### TAPE AND REEL INFORMATION





#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



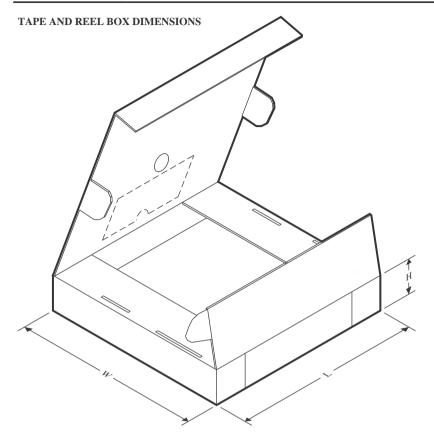
*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM248DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM348DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM348NSR	SOP	NS	14	2000	330.0	16.4	8.45	10.55	2.5	12.0	16.2	Q1



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# PACKAGE MATERIALS INFORMATION

7-Dec-2024



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM248DR	SOIC	D	14	2500	356.0	356.0	35.0
LM348DR	SOIC	D	14	2500	353.0	353.0	32.0
LM348NSR	SOP	NS	14	2000	356.0	356.0	35.0

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### TUBE



### - B - Alignment groove width

#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
LM148FKB	FK	LCCC	20	55	506.98	12.06	2030	NA
LM248N	N	PDIP	14	25	506	13.97	11230	4.32
LM348N	N	PDIP	14	25	506	13.97	11230	4.32

# **D0014A**



# **PACKAGE OUTLINE**

### SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- 5. Reference JEDEC registration MS-012, variation AB.



# D0014A

# **EXAMPLE BOARD LAYOUT**

## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# D0014A

# **EXAMPLE STENCIL DESIGN**

## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



### MECHANICAL DATA

### PLASTIC SMALL-OUTLINE PACKAGE

### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# FK 20

### 8.89 x 8.89, 1.27 mm pitch

# **GENERIC PACKAGE VIEW**

## LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





# **GENERIC PACKAGE VIEW**

# CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



# J0014A



# **PACKAGE OUTLINE**

### CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
  Falls within MIL-STD-1835 and GDIP1-T14.



# J0014A

# **EXAMPLE BOARD LAYOUT**

## CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





## N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.



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